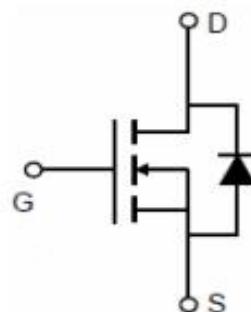


## N-Channel Enhancement Mode Power MOSFET

### Description

The MXN3060 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$ , With low gate charge. It can be used in a wide variety Of applications.



### General Features

$V_{DS} = 30V, I_D = 80A$

$R_{DS(ON)} (\text{Typ.}) 5.0\text{m}\Omega @ V_{GS}=10V$

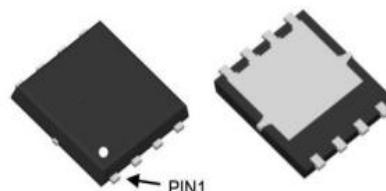
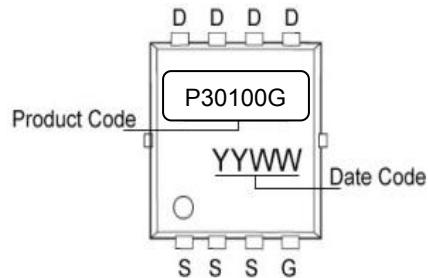
$R_{DS(ON)} (\text{Typ.}) 6\text{m}\Omega @ V_{GS}=-4.5V$

Low density cell design

Fully characterized avalanche voltage and current

Good stability and uniformity with high  $E_{AS}$

Excellent package for good heat dissipation



DFN5X6-8L top&bottom view

### Application

Power switching application

Hard switched and high frequency circuits

Uninterruptible power supply

### Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	80	A
Drain Current-Pulsed (Note 1)	$I_{DM}$	150	A
Maximum Power Dissipation	$P_D$	42	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

### Thermal CharacteristicE

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	3.0	°C/W
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**Electrical Characteristics ( $T_A=25^\circ\text{C}$  unless otherwise noted)**

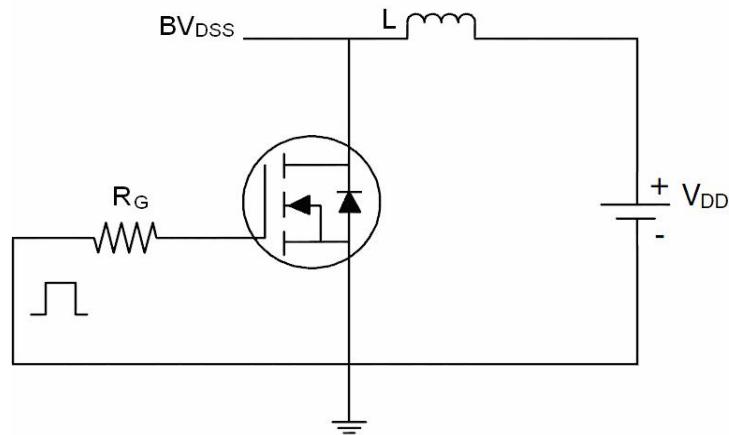
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	30	-	-	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=-24\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA
<b>On Characteristics</b> <small>(Note 3)</small>						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.0	1.4	2.0	V
Drain-Source On-State Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$	-	5.0	6.5	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=20\text{A}$	-	6.0	9.0	$\text{m}\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=20\text{A}$	-	57	-	S
<b>Dynamic Characteristics</b> <small>(Note 4)</small>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	1950	-	PF
Output Capacitance	$C_{\text{oss}}$		-	310	-	PF
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	240	-	PF
<b>Switching Characteristics</b> <small>(Note 4)</small>						
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=15\text{V}, R_{\text{L}}=15\Omega$ $V_{\text{GS}}=10\text{V}, R_{\text{G}}=2.5\Omega$	-	8.1	-	nS
Turn-on Rise Time	$t_{\text{r}}$		-	8.6	-	nS
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	30	-	nS
Turn-Off Fall Time	$t_{\text{f}}$		-	9	-	nS
Total Gate Charge	$Q_{\text{g}}$	$V_{\text{DS}}=15\text{V}, I_{\text{D}}=20\text{A}, V_{\text{GS}}=10\text{V}$	-	37	-	nC
Gate-Source Charge	$Q_{\text{gs}}$		-	4.8	-	nC
Gate-Drain Charge	$Q_{\text{gd}}$		-	11	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <small>(Note 3)</small>	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{s}}=20\text{A}$	-		1.2	V
Diode Forward Current <small>(Note 2)</small>	$I_{\text{s}}$		-	-	60	A
Reverse Recovery Time	$t_{\text{rr}}$	$T_{\text{J}} = 25^\circ\text{C}, \text{IF} = 20\text{A}$ $dI/dt = 100\text{A}/\mu\text{s}$ <small>(Note 3)</small>	-	26	-	nS
Reverse Recovery Charge	$Q_{\text{rr}}$		-	34	-	nC
Forward Turn-On Time	$t_{\text{on}}$	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

**Notes:**

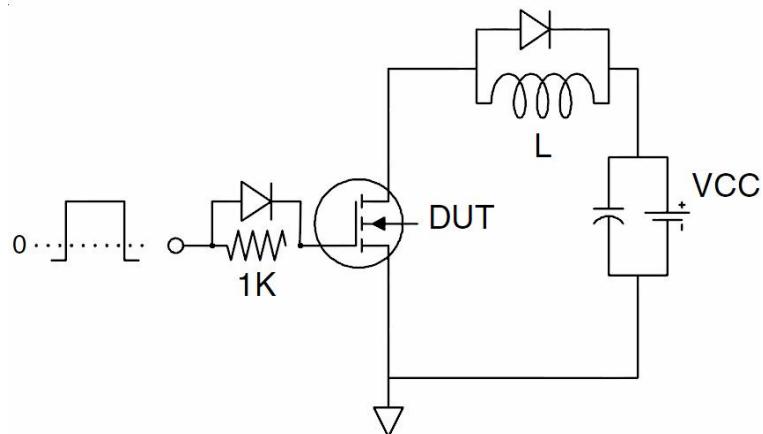
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

### Test circuit

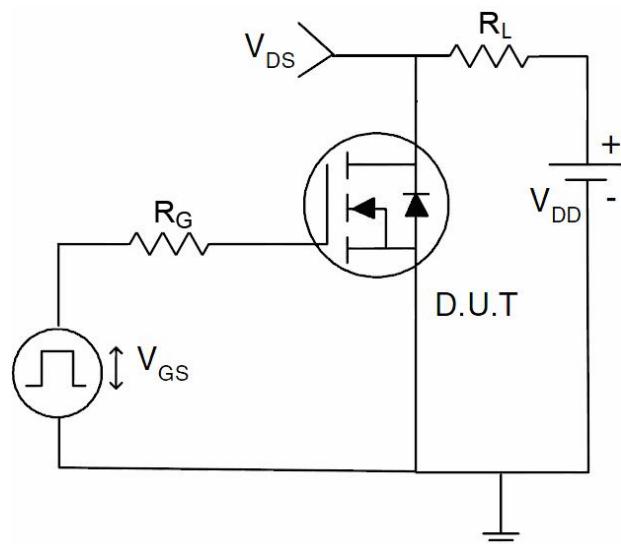
#### 1) E<sub>AS</sub> Test Circuit

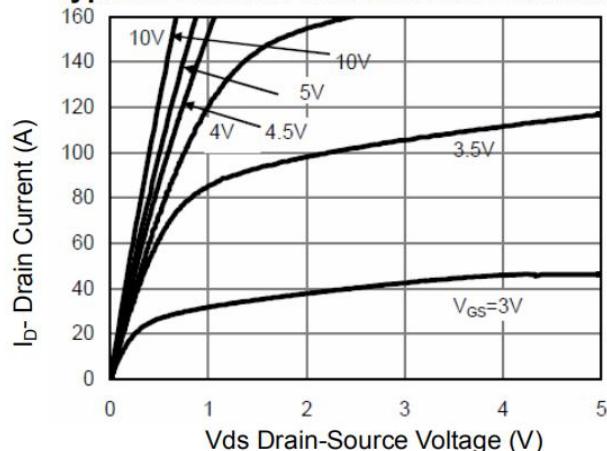
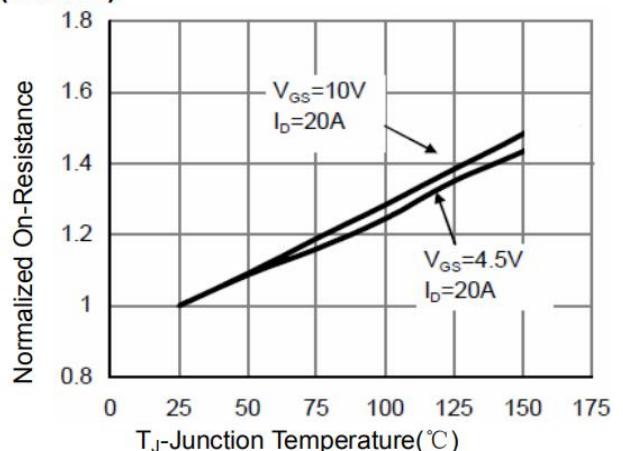
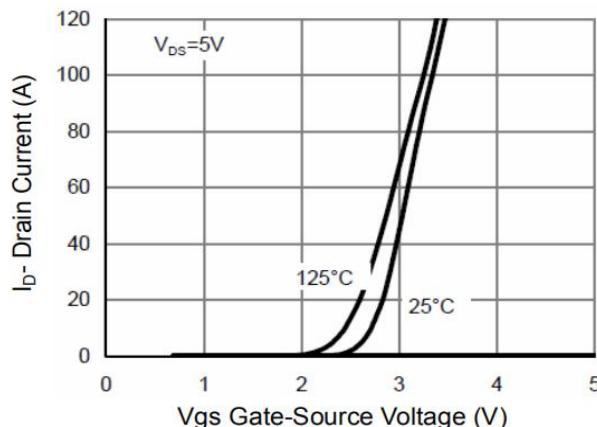
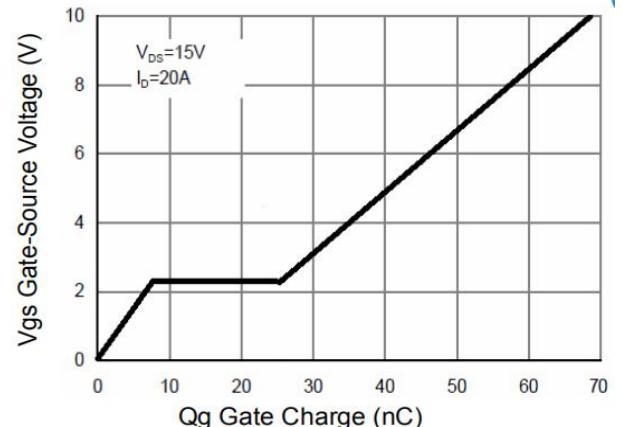
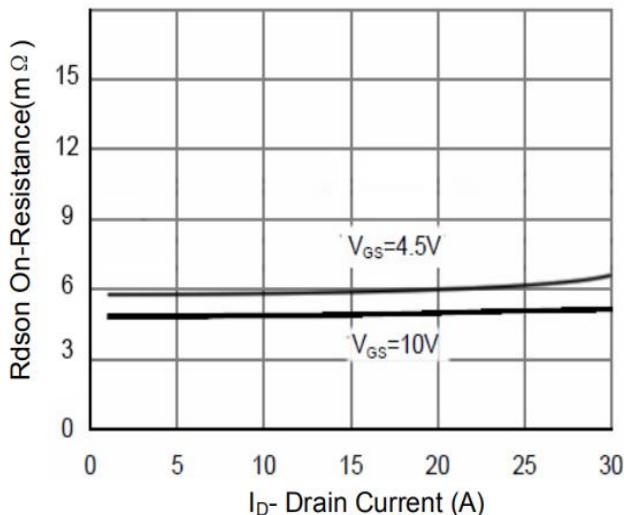
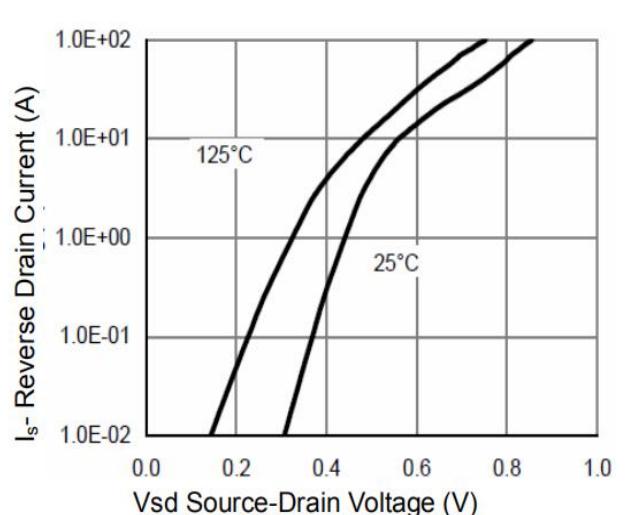


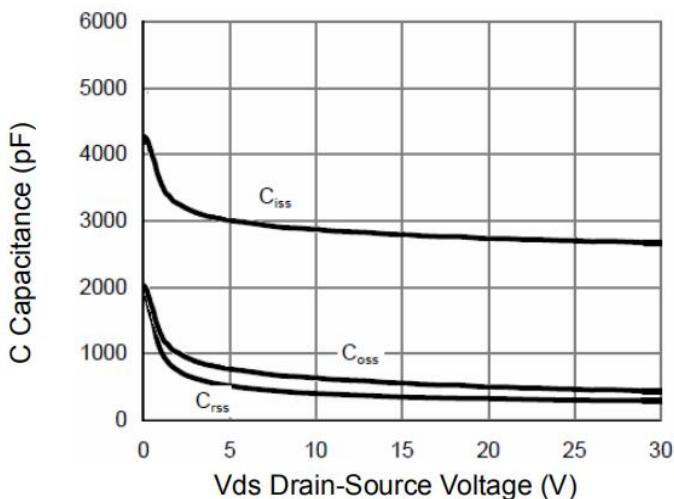
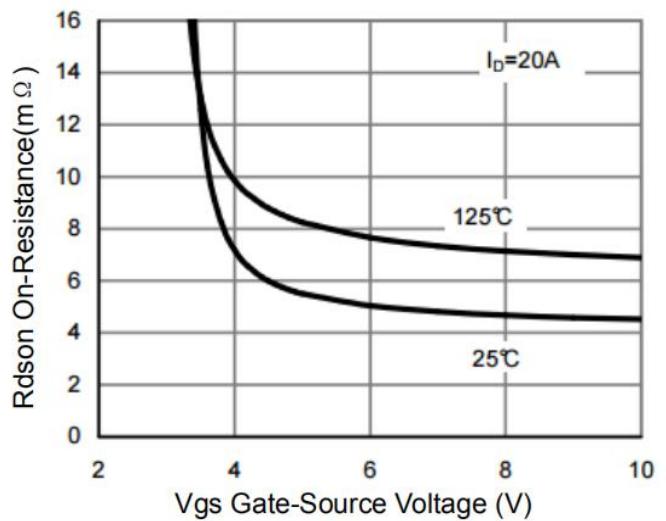
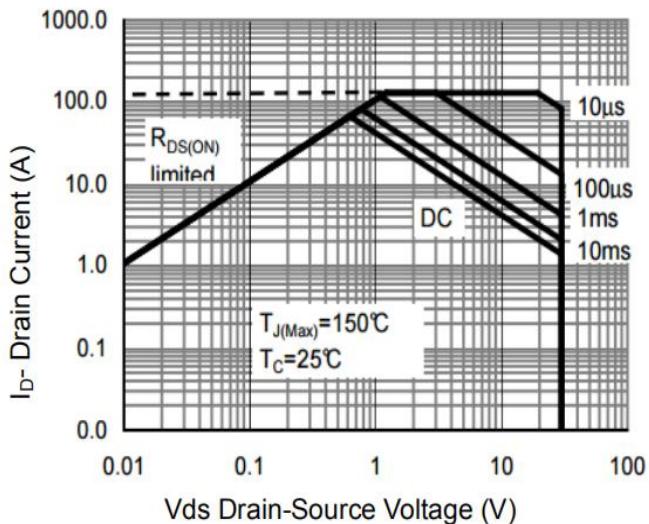
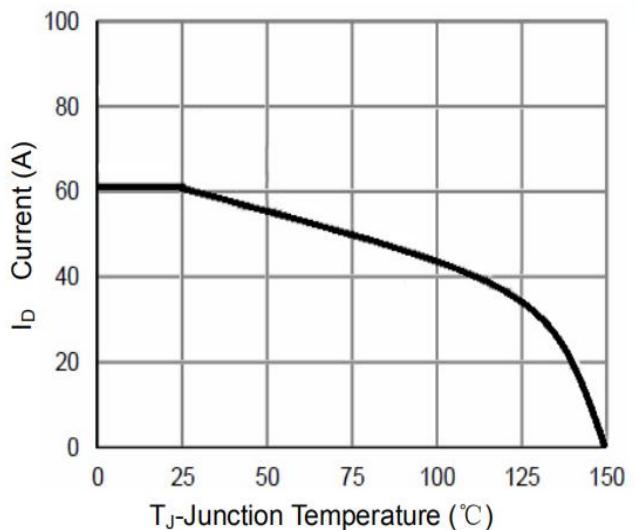
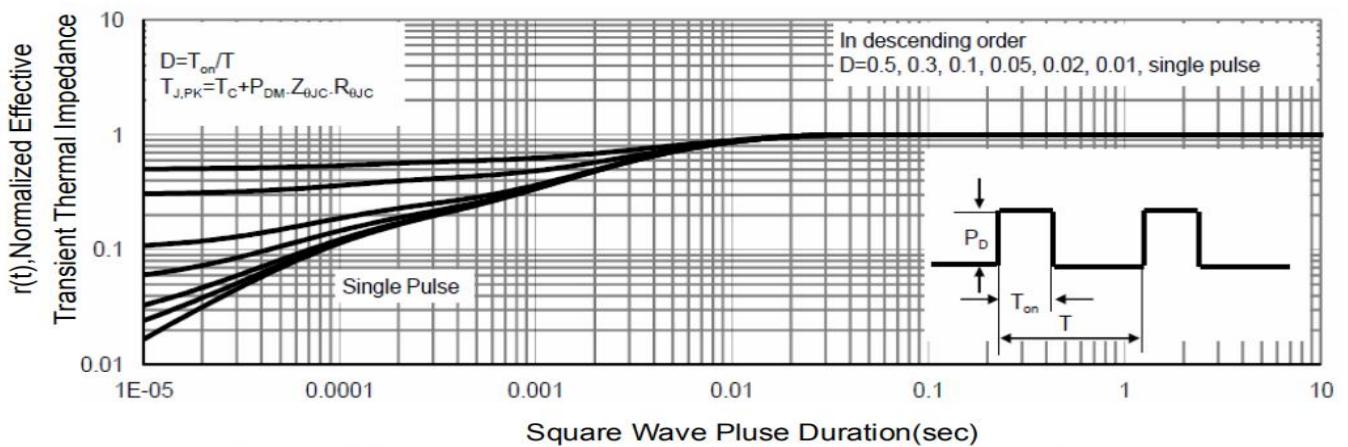
#### 2) Gate Charge Test Circuit



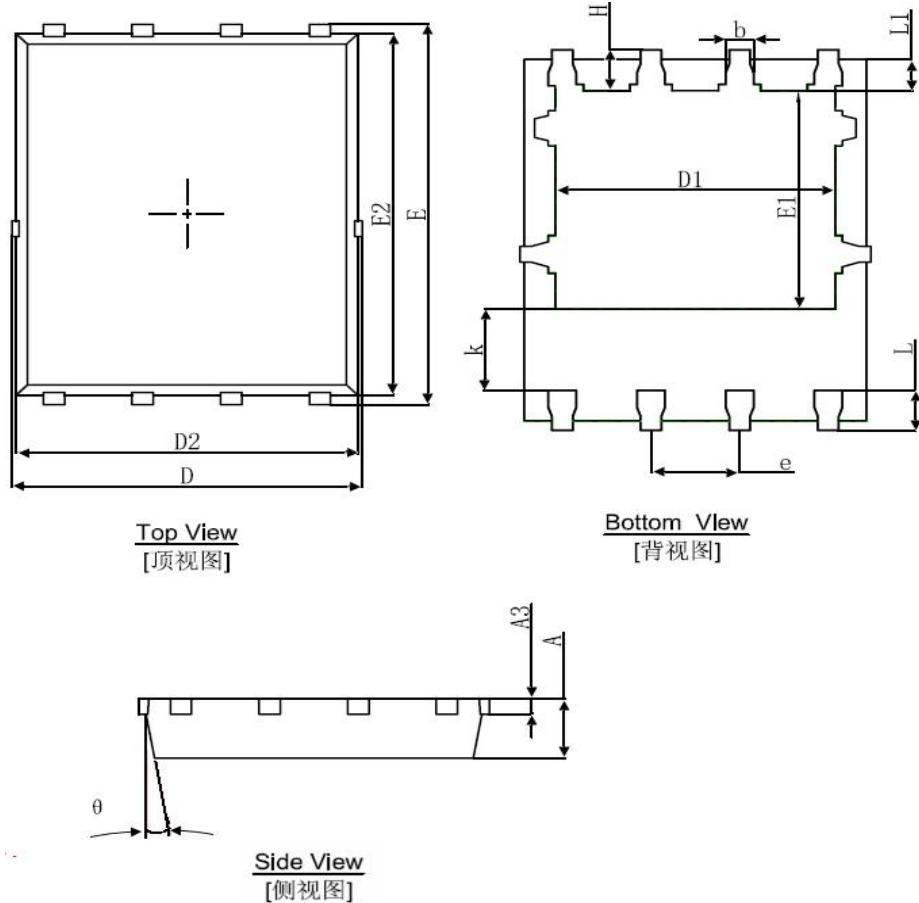
#### 3) Switch Time Test Circuit



**Typical Electrical and Thermal Characteristics (Curves)**

**Figure 1 Output Characteristics**

**Figure 4 Rdson-JunctionTemperature**

**Figure 2 Transfer Characteristics**

**Figure 5 Gate Charge**

**Figure 3 Rdson- Drain Current**

**Figure 6 Source- Drain Diode Forward**


**Figure 7 Capacitance vs Vds**

**Figure 9 Rdson vs Gate-Source Voltage**

**Figure 8 Safe Operation Area**

**Figure 10 Current- Junction Temperature**

**Figure 11 Normalized Maximum Transient Thermal Impedance**

## DFN5X6-8L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	8°		8°	